

## 1. General description

Ultrafast power diode in a 2-lead TO247 plastic package



## 2. Features and benefits

- Fast switching
- Low leakage current
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses in associated MOSFET or IGBT

## 3. Applications

- Active PFC in air conditioner
- High frequency switched-mode power supplies
- Power Factor Correction (PFC)

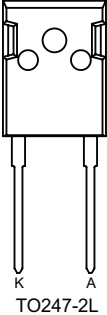
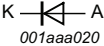
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
<b>Absolute maximum rating</b>							
$V_{RRM}$	repetitive peak reverse voltage			650			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 134$ °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		30			A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25$ $\mu$ s; $T_{mb} \leq 134$ °C; square-wave pulse		60			A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(initial)} = 25$ °C; sine-wave pulse; <a href="#">Fig. 4</a>		350			A
		$t_p = 8.3$ ms; $T_{j(initial)} = 25$ °C; sine-wave pulse		385			A
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward voltage	$I_F = 30$ A; $T_j = 25$ °C; <a href="#">Fig. 6</a>		-	1.34	1.55	V
		$I_F = 30$ A; $T_j = 150$ °C; <a href="#">Fig. 6</a>		-	1.06	1.27	V
<b>Dynamic characteristics</b>							
$t_{rr}$	reverse recovery time	$I_F = 1$ A; $V_R = 30$ V; $di_F/dt = 200$ A/ $\mu$ s; $T_j = 25$ °C; <a href="#">Fig. 7</a>		-	27	-	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p style="text-align: center;">K                      A TO247-2L</p>	 <p style="text-align: center;">K — &lt;— A 001aaa020</p>
2	A	anode		
mb	mb	mounting base; connected to cathod		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYV30MW-650PT2	TO247-2L	BYV30MW-650PT2Q	Tube	30	TO247L-2L (L)	10-Nov-2020
					TO247P-2L (P)	31-Mar-2023

## 7. Marking

Table 4. Marking codes

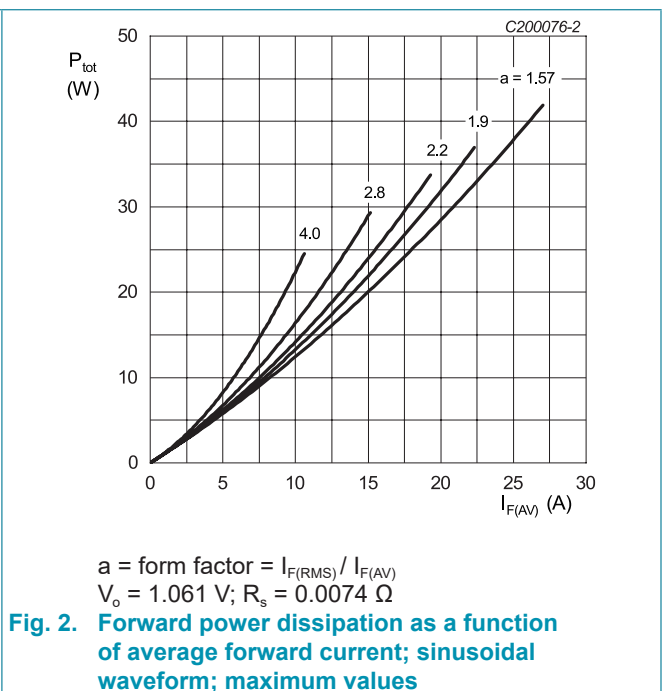
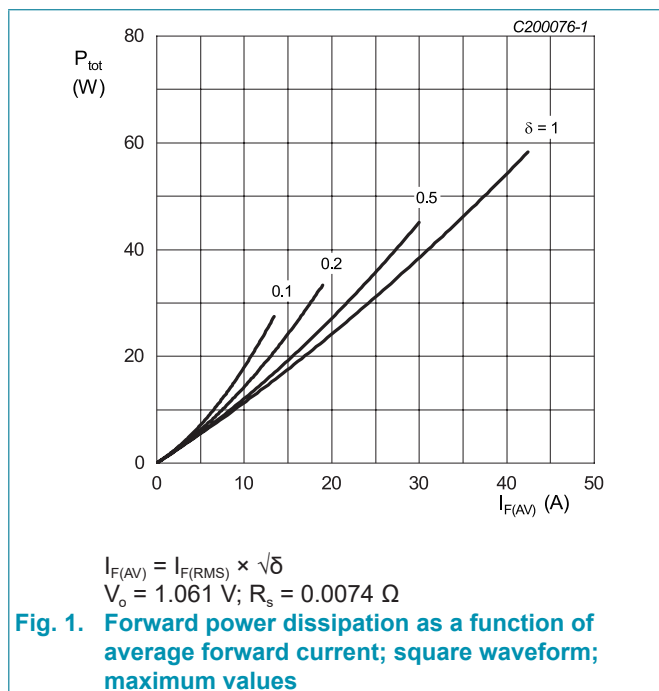
Type number	Marking codes	
	Assembly factory: L	Assembly factory: P
BYV30MW-650PT2	BYV30MW 650PT2 PjLxxxx xx	BYV30MW 650PT2 PjPxxxx xx

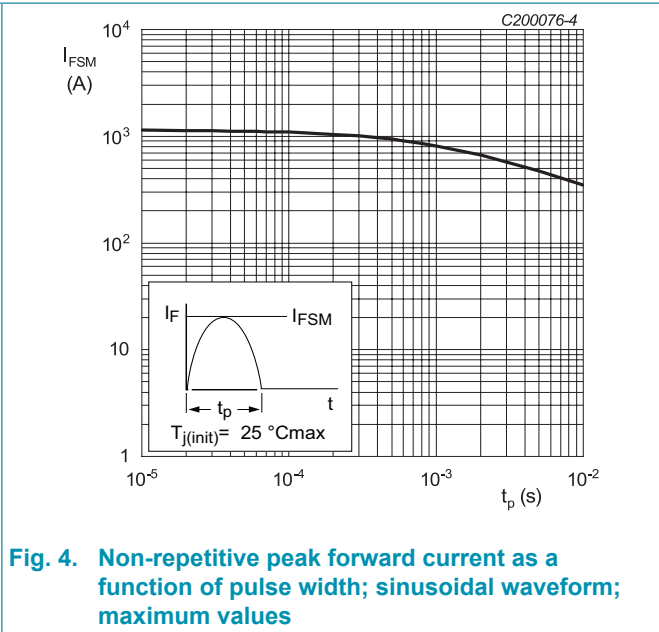
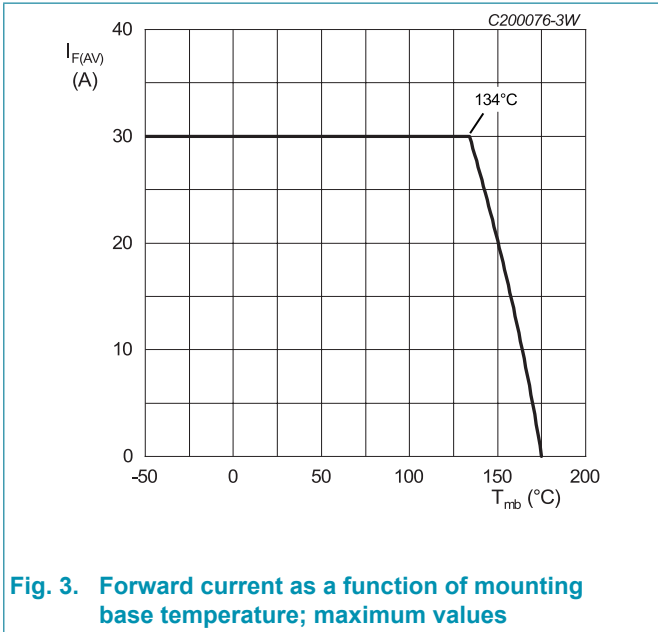
## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			650	V
$V_{RWM}$	crest working reverse voltage			650	V
$V_R$	reverse voltage	DC		650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 134\text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		30	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 134\text{ }^\circ\text{C}$ ; square-wave pulse		60	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>		350	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse		385	A
$T_{stg}$	storage temperature			-65 to 175	$^\circ\text{C}$
$T_j$	junction temperature			-65 to 175	$^\circ\text{C}$





### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>		-	-	0.91	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	40	-	K/W

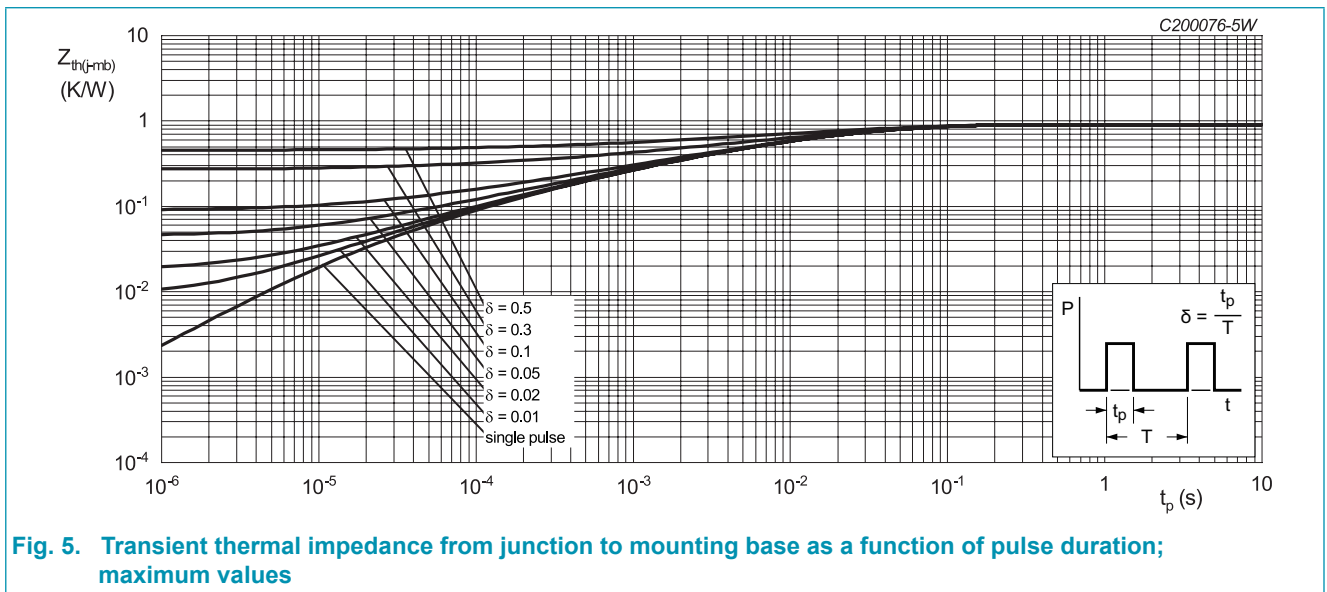
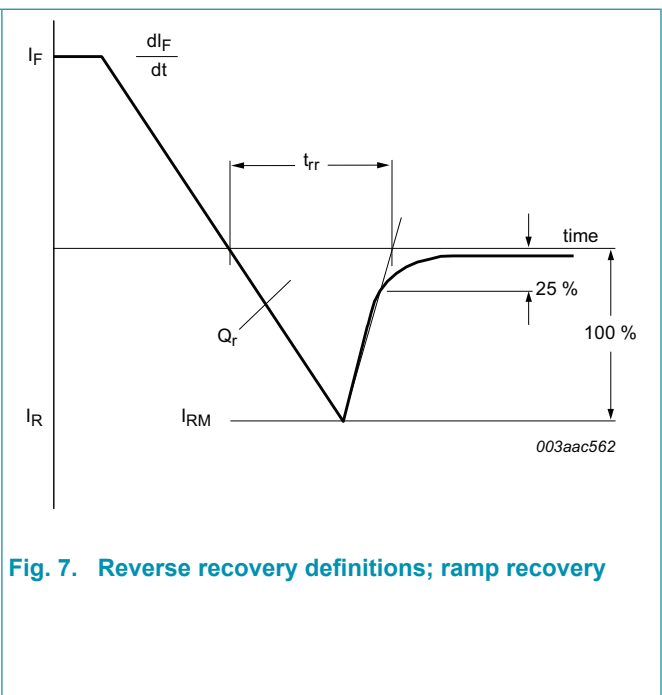
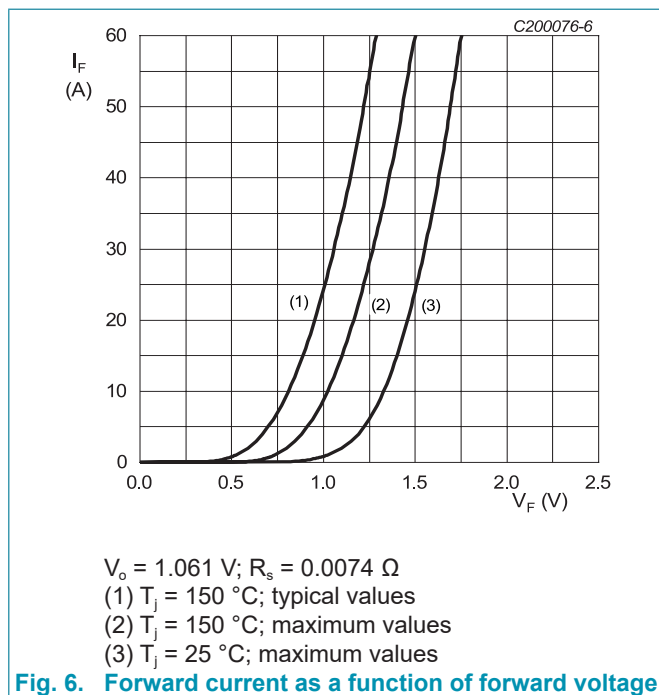


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration; maximum values

### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 30 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-	1.34	1.55	V
		I <sub>F</sub> = 30 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 6</a>		-	1.06	1.27	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C		-	0.67	30	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 150 °C		-	-	1	mA
<b>Dynamic characteristics</b>							
Q <sub>r</sub>	reverse charge	I <sub>F</sub> = 30 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	159.3	-	nC
		I <sub>F</sub> = 30 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 125 °C; <a href="#">Fig. 7</a>		-	599.3	-	nC
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A; V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 200 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	27	-	ns
		I <sub>F</sub> = 30 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	78	-	ns
		I <sub>F</sub> = 30 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 125 °C; <a href="#">Fig. 7</a>		-	133	-	ns
I <sub>RM</sub>	peak reverse recovery current	I <sub>F</sub> = 30 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	4.1	-	A
		I <sub>F</sub> = 30 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 100 A/μs; T <sub>j</sub> = 125 °C; <a href="#">Fig. 7</a>		-	9.1	-	A
E <sub>as</sub>	non-repetitive avalanche energy	T <sub>j(initial)</sub> = 25 °C		30	-	-	mJ

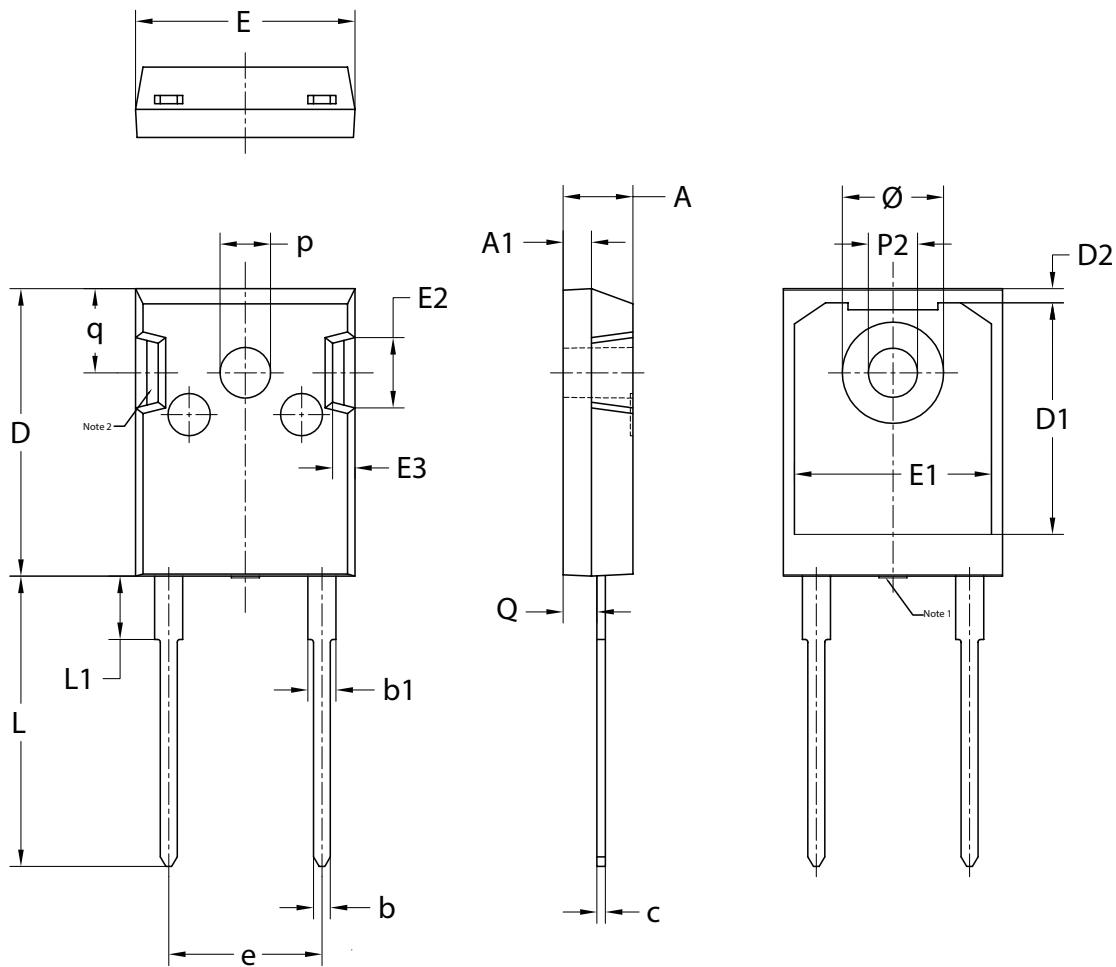


### 11. Package outline

Assembly factory: L

Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 2 leads TO-247

TO247-2L



UNIT	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	D <sub>1</sub> ⊙	D <sub>2</sub>	E	E <sub>1</sub>	E <sub>2</sub>	E <sub>3</sub>	e	L	L <sub>1</sub>	P <sub>2</sub>	p	Q	q	Ø
mm	5.20	2.10	1.40	2.20	0.70	20.60	16.20	1.20	15.75	14.22	5.20	1.80	10.90	20.72	4.75	3.60	3.70	2.60	6.18	7.30
	4.70	1.90	1.00	1.80	0.50	20.30	16.87	0.80	15.45	13.82	4.80	1.40	BSC	20.22	4.25	3.40	3.50	2.20	5.78	7.10

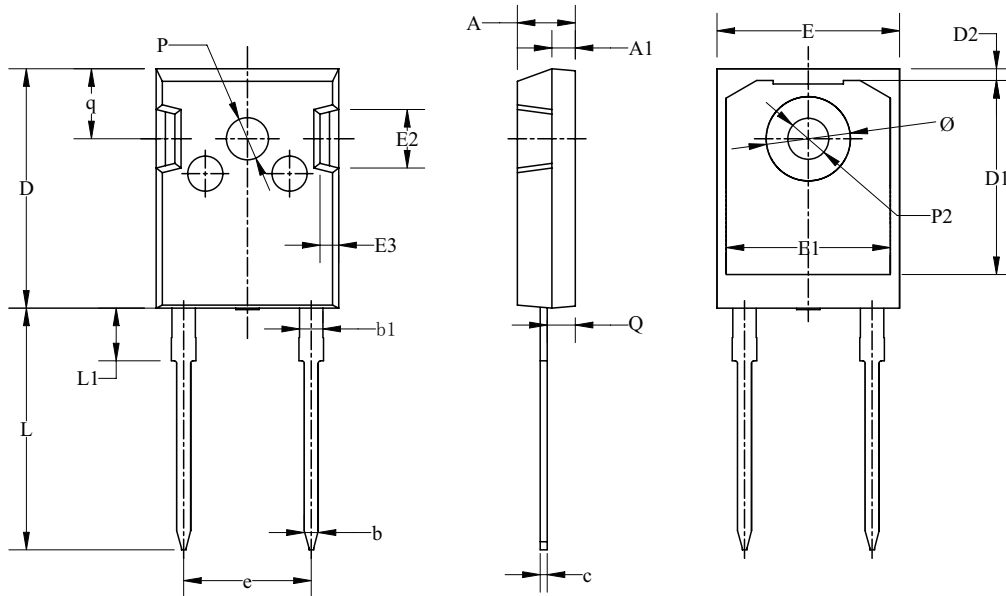
Note:

1. Mold resin protrusion max 0.127mm.
2. Metal exposed with Sn plating.

Assembly factory: P

Plastic single-ended through-hole pack age; headsink mounted; 1 mounting hole; 2 leads TO-247

TO247-2L



Dim	All Dimensions in Millimeters		
	Min	Typ	Max
A	4.70	4.95	5.20
A1	1.90	2.00	2.10
b	1.00	1.20	1.40
b1	1.80	2.00	2.20
c	0.50	0.60	0.70
D	20.30	20.45	20.60
D1	16.20	16.58	16.87
D2	0.80	1.00	1.20
E	15.45	15.60	15.75
E1	13.82	14.02	14.22
E2	4.80	5.00	5.20
E3	1.40	1.60	1.80
e	10.90 BSC		
L	20.40	20.65	20.90
L1	4.25	4.50	4.75
P2	3.40	3.50	3.60
P	3.50	3.60	3.70
Q	2.20	2.40	2.60
q	5.78	5.98	6.18
Ø	7.10	7.19	7.30



## 12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Date of release: 25 January 2024

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